

1. Please cancel.
2. Please cancel.
3. Please cancel.
4. Please cancel.
5. Please cancel.
6. Please cancel.
7. Please cancel.
8. Please cancel.
9. Please cancel.
10. Please cancel.
11. Please cancel.
12. Please cancel.
13. Please cancel.
14. Please cancel.
15. Please cancel.
16. Please cancel.
17. Please cancel.
18. Please cancel.

19. A wafer processing apparatus comprising:

a chuck including a surface, an electrical coupling adjacent the surface, and electrical interconnect configured to connect with the electrical coupling of the chuck and conduct a signal within the chuck;

an intermediate member adapted to receive a wafer and the intermediate member having a first surface and a second surface and the intermediate member including:

an electrical coupling adjacent the first surface and configured to couple with the electrical coupling of the chuck;

an electrical coupling adjacent the second surface; and

an electrical interconnect configured to connect the electrical coupling adjacent the first surface and the electrical coupling adjacent the second surface; and

a wafer configured to couple with the second surface of the intermediate member, the wafer including a sensor and an electrical coupling configured to provide electrical connection of the sensor with the electrical coupling of the second surface of the intermediate member.

20. The wafer processing apparatus according to claim 19 further comprising a data gathering device coupled with the electrical coupling of the chuck and configured to receive the signal.

21. The wafer processing apparatus according to claim 20 further comprising a contact plate configured to communicate the signal intermediate the chuck and the data gathering device.

22. The wafer processing apparatus according to claim 19 wherein the sensor comprises a resistance temperature device.

23. The wafer processing apparatus according to claim 19 wherein the wafer comprises a calibration wafer.

24. The wafer processing apparatus according to claim 19 wherein the electrical interconnect comprises a conductive column configured to extend outward from plural surfaces of the chuck.

25. The wafer processing apparatus according to claim 24 further comprising a contact plate including circuitry configured to provide electrical connection with electrical couplings of the chuck.

26. A wafer processing apparatus comprising:

a chuck including a surface, a plurality of electrical couplings adjacent the surface, and a plurality of electrical interconnects configured to connect with respective electrical couplings of the chuck and conduct signals within the chuck;

an intermediate member adapted to receive a wafer and the intermediate member having a first surface and a second surface and the intermediate member including:

a plurality of electrical couplings adjacent the first surface and configured to couple with respective electrical couplings of the chuck;

a plurality of electrical couplings adjacent the second surface; and

a plurality of electrical interconnects configured to electrically connect the electrical couplings of the first surface with respective electrical couplings of the second surface;

a calibration wafer configured to couple with the second surface of the intermediate member, the calibration wafer including a plurality of resistance temperature devices configured to generate process signals, and a plurality of electrical connections configured to electrically connect the resistance temperature devices with respective electrical couplings of the second surface of the intermediate member; and

a data gathering device coupled with the electrical interconnects of the chuck and configured to receive the process signals from the resistance temperature devices through the intermediate member and the chuck.

- 27. Canceled.
- 28. Canceled.
- 29. Canceled.
- 30. Canceled.
- 31. Canceled.
- 32. Canceled.
- 33. Canceled.
- 34. Canceled.
- 35. Canceled.
- 36. Canceled.
- 37. Canceled.
- 38. Canceled.
- 39. Canceled.
- 40. Canceled.
- 41. Canceled.
- 42. Canceled.
- 43. Canceled.
- 44. Canceled.
- 45. Canceled.
- 46. Canceled.
- 47. Canceled.

- 48. Canceled.
- 49. Canceled.
- 50. Canceled.
- 51. Canceled.
- 52. Canceled.
- 53. Canceled.
- 54. Canceled.
- 55. Canceled.
- 56. Canceled.
- 57. Please cancel.
- 58. Please cancel.
- 59. Please cancel.

60. ~~An electronic device workpiece processing apparatus comprising:
a chuck including a surface, an electrical coupling adjacent the surface, and
electrical interconnect configured to connect with the electrical coupling of the chuck and
conduct a signal within the chuck;
an intermediate member having a first surface and a second surface and the
intermediate member including:
an electrical coupling adjacent the first surface and configured to couple with
the electrical coupling of the chuck;~~

~~an electrical coupling adjacent the second surface; and
an electrical interconnect configured to connect the electrical coupling
adjacent the first surface and the electrical coupling adjacent the second surface; and
an electronic device workpiece configured to couple with the second surface of the
intermediate member, the electronic device workpiece including a sensor comprising a
resistance temperature device, and an electrical coupling configured to provide electrical
connection of the sensor with the electrical coupling of the second surface of the
intermediate member.~~

61. Please cancel.

62. Please cancel.

63. (New) An electronic device workpiece processing apparatus comprising:
an electronic workpiece including a sensor and an electrical coupling; and
an intermediate member including a surface having an electrical coupling;
wherein the electrical coupling of the electronic workpiece is configured to provide
electrical connection of the sensor with the electrical coupling of the surface of the
intermediate member.